

Title (en)
SENSOR CHIP WITH ADDITIONAL HEATING ELEMENT, METHOD FOR PREVENTING A SENSOR CHIP FROM BEING SOILED, AND USE OF AN ADDITIONAL HEATING ELEMENT ON A SENSOR CHIP

Title (de)
SENSORCHIP MIT ZUSATZHEIZER BZW. VERFAHREN ZUR VERMEIDUNG VON VERSCHMUTZUNGEN AUF EINEM SENSORCHIP BZW. VERWENDUNG EINES ZUSATZHEIZERS AUF EINEM SENSORCHIP

Title (fr)
PUCE DE DETECTION AVEC ELEMENT CHAUFFANT ADDITIONNEL, PROCEDE PERMETTANT D'EVITER LA FORMATION DE SALISSURES SUR UNE PUCE DE DETECTION ET UTILISATION D'UN ELEMENT CHAUFFANT SUPPLEMENTAIRE SUR UNE PUCE DE DETECTION

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EP 1370835 A2 20031217 (DE)

Application
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Abstract (en)
[origin: WO02073140A2] In conventional sensor chips contaminations of a flowing medium can deposit in the area of the sensor and can permanently soil it, resulting in a negative influence on the measuring behavior of the membrane. The inventive sensor chip (1) is characterized in that an additional heating element (39) is provided that is arranged upstream and at a distinct distance to the sensor area. As a result, the contaminations of the flowing medium deposit in the area of the additional heating element (39) and are thus prevented from reaching the sensor area (17).

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G01F 1/684

IPC 8 full level
G01F 1/68 (2006.01); **G01F 1/684** (2006.01); **G01F 1/692** (2006.01); **G01F 1/696** (2006.01); **G01F 1/699** (2006.01)

CPC (source: EP KR US)
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Citation (search report)
See references of WO 02073140A2

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